



P-Channel 20 V (D-S) MOSFET

MOSFET PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)		
- 20	$0.112 \text{ at V}_{GS} = -4.5 \text{ V}$	- 3.1	3.3 nC		
- 20	0.142 at $V_{GS} = -2.5 \text{ V}$	- 2.7	3.3 110		

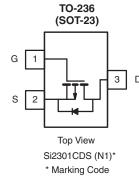
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



APPLICATIONS

· Load Switch



Ordering Information: Si2301CDS-T1-E3 (Lead (Pb)-free)

Si2301CDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	- 20	V	
Gate-Source Voltage		V _{GS}	± 8	
	T _C = 25 °C		- 3.1	
Continuous Drain Current (T _{.J} = 150 °C)	T _C = 70 °C		- 2.5	
Continuous Diain Current (1) = 130 C)	T _A = 25 °C	I _D	- 2.3 ^{b, c}	
	T _A = 70 °C		- 1.8 ^{b, c}	А
Pulsed Drain Current	I _{DM} - 10	- 10		
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	- 1.3	
Continuous Source-Diam Diode Current	T _A = 25 °C	I _S	- 0.72 ^{b, c}	
	T _C = 25 °C		1.6	
Maximum Davier Dissination	T _C = 70 °C	ь Г	1.0	w
Maximum Power Dissipation	T _A = 25 °C	P _D	0.86 ^{b, c}	VV
	T _A = 70 °C		0.55 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stq}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	120	145	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	62	78	G/VV		

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 175 $^{\circ}\text{C/W}.$

Si2301CDS

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J. 050 A		- 18			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.2		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = -250 \mu A$	- 0.4		- 1	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zovo Coto Voltogo Droin Current		V _{DS} = - 20 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = - 20 V, V_{GS} = 0 V, T_{J} = 55 °C			- 10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le$ - 5 V, V_{GS} = - 4.5 V	- 6			Α	
Drain Course On Ctota Decistoras	_	V _{GS} = - 4.5 V, I _D = - 2.8 A	0.090		0.112		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 2.0 A		0.110	0.142	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 2.8 A		9.5		S	
Dynamic ^b							
Input Capacitance	C _{iss}			405		pF	
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		75			
Reverse Transfer Capacitance	C _{rss}			55			
Total Cata Charga	0	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -3 \text{ A}$	5.5		10		
Total Gate Charge	Q _g			3.3	6	nC	
Gate-Source Charge	Q _{gs}	V_{DS} = - 10 V, V_{GS} = - 2.5 V, I_D = - 3 A		0.7			
Gate-Drain Charge	Q_{gd}			1.3			
Gate Resistance	R_g	f = 1 MHz		6.0		Ω	
Turn-On Delay Time	t _{d(on)}			11	20		
Rise Time	t _r	V_{DD} = - 10 V, R_L = 10 Ω		35	60	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D = -1 A$, $V_{GEN} = -4.5 V$, $R_g = 1 \Omega$		30	50		
Fall Time	t _f			10	20		
Drain-Source Body Diode Characteristi	cs			•		•	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.3		
Pulse Diode Forward Current ^a	I _{SM}				- 10	A	
Body Diode Voltage	V _{SD}	I _S = - 0.7 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			30	50	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 000 A 41/44 400 A/44 T 07:00		25	50	nC	
Reverse Recovery Fall Time	t _a	$I_F = -3.0 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15			
Reverse Recovery Rise Time	t _b			15		ns	

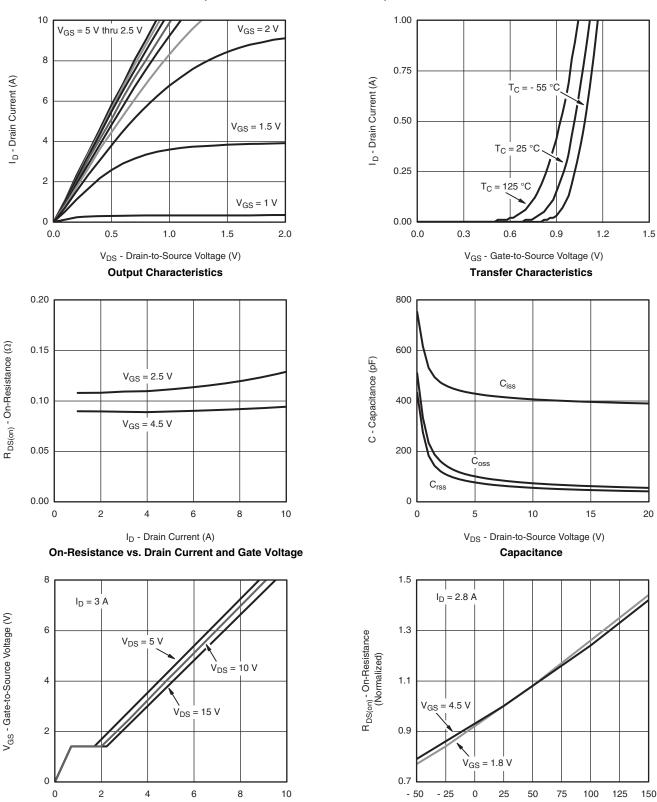
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Q_g - Total Gate Charge (nC)

Gate Charge

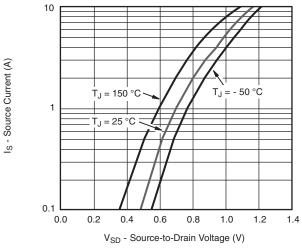
T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

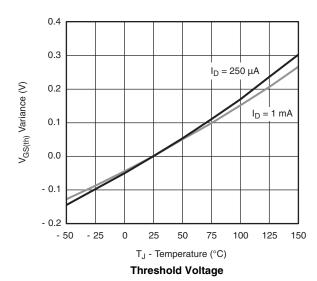
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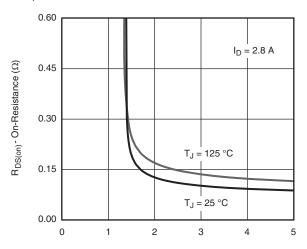
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



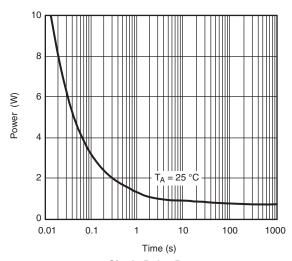
Source-Drain Diode Forward Voltage



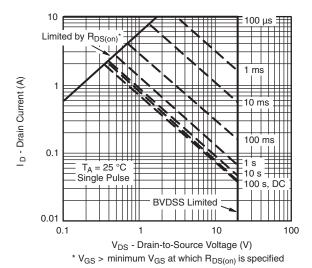


V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage

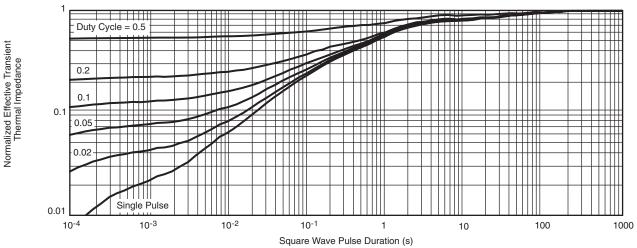


Single Pulse Power

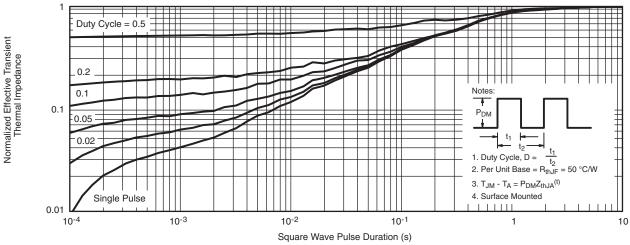




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.9	5 BSC	0.037	4 Ref	
e ₁	1.9	0 BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.6	0.64 Ref		0.025 Ref	
S	0.5	50 Ref	0.020 Ref		
q	3°	8°	3°	8°	
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ECN: S-03946-Rev. K, 09-Jul-01

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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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